

DFW



PATENT
YOR920030206

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

In re Application of	:	Larry Shungwei Mok
Serial Number	:	10/784,624
Filing Date	:	02/23/2004
Examiner	:	Tho V. Duong
Group Art Unit	:	3753
For	:	HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

Sir:

In response to the Official Action dated August 25, 2006, please amend the above-identified application as follows:

In the Drawings:

Please insert the enclosed corrected drawings into this Application. The pages are labeled as "Replacement Pages."

In the Claims:

Please amend Claims 1 – 9 as set forth in the Appendix attached hereto.

REMARKS

Formal Drawings are enclosed. These are marked as "Replacement Pages" as noted above. They contain all of the features found in the informal drawings that were filed initially with the application. No new features/matter is present in these drawings.

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